

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently amended) A light emitting diode, comprising:
  - a semiconductor substrate;
  - a light-emitting region including an active layer provided between a first conductivity type cladding layer formed over [[on]] the semiconductor substrate and a second conductivity type cladding layer;
  - a transparent conductive film made of a metal oxide and located over the light-emitting region;
  - a first electrode formed on the upper side of the transparent conductive film;
  - a second electrode formed on the whole or a part of the bottom of the semiconductor substrate;
  - a layer for preventing exfoliation of the transparent conductive film, the preventing layer being made of a compound semiconductor containing at least aluminum and located between the light-emitting region and the transparent conductive film, the preventing layer having a high carrier concentration; and
  - an undoped layer or a low carrier concentration layer formed between the active layer and the second conductivity type cladding layer, wherein the undoped layer or the low carrier concentration layer is a layer other than the active layer and comprises a bandgap greater than the active layer.
2. (Original) The light emitting diode as defined in claim 1, wherein:
  - the preventing layer contains a conductivity type determination impurity at a concentration of  $1 \times 10^{19} \text{ cm}^{-3}$  or higher.
3. (Original) The light emitting diode as defined in claim 1, wherein:
  - the preventing layer has a film thickness of 300 nm or less.
4. (Original) The light emitting diode as defined in claim 2, wherein:
  - the preventing layer has a film thickness of 300 nm or less.

5. (Original) The light emitting diode as defined in claim 1, wherein:  
the transparent conductive film is made of indium tin oxide.
6. (Original) The light emitting diode as defined in claim 2, wherein:  
the transparent conductive film is made of indium tin oxide.
7. (Original) The light emitting diode as defined in claim 1, wherein:  
the preventing layer is made of an arsenic compound.
8. (Original) The light emitting diode as defined in claim 2, wherein:  
the preventing layer is made of an arsenic compound.
9. (Original) The light emitting diode as defined in claim 1, wherein:  
the light-emitting region is made of  $(\text{Al}_x\text{Ga}_{1-x})_y\text{In}_{1-y}\text{P}$  ( $0 \leq X \leq 1$ ,  $0 \leq Y \leq 1$ ).
10. (Original) The light emitting diode as defined in claim 2, wherein:  
the light-emitting region is made of  $(\text{Al}_x\text{Ga}_{1-x})_y\text{In}_{1-y}\text{P}$  ( $0 \leq X \leq 1$ ,  $0 \leq Y \leq 1$ ).
11. (Original) The light emitting diode as defined in claim 1, wherein:  
the preventing layer is an AlGaAs layer having a bandgap which is smaller than that of the active layer; and  
the AlGaAs layer is made of  $\text{Al}_x\text{Ga}_{1-x}\text{As}$  ( $0.01 \leq X \leq 0.43$ ).
12. (Previously presented) The light emitting diode as defined in claim 1, wherein:  
the preventing layer has a carrier concentration of  $1 \times 10^{19} \text{ cm}^{-3}$  or higher.
13. (Original) The light emitting diode as defined in claim 11, wherein:  
the AlGaAs layer has a carrier concentration of  $1 \times 10^{19} \text{ cm}^{-3}$  or higher.
14. (Previously presented) The light emitting diode as defined in claim 1, wherein:  
the preventing layer is added with at least one of Zn, Be, and Mg.
15. (Original) The light emitting diode as defined in claim 11, wherein:  
the AlGaAs layer is added with at least one of Zn, Be, and Mg.

16. (Previously presented) The light emitting diode as defined in claim 1, wherein:  
the preventing layer is added with at least one of Zn, Be and Mg, and C; and  
C is autodoped.
17. (Original) The light emitting diode as defined in claim 11, wherein:  
the AlGaAs layer is added with at least one of Zn, Be and Mg, and C; and  
C is autodoped.
18. (Previously presented) The light emitting diode as defined in claim 1, wherein:  
the preventing layer is formed at a growth temperature of 600°C or lower.
19. (Original) The light emitting diode as defined in claim 11, wherein:  
the AlGaAs layer is formed at a growth temperature of 600°C or lower.
20. (Previously presented) The light emitting diode as defined in claim 1, wherein:  
the preventing layer is formed at a V/III ratio in raw materials of 50 or less at the time  
of growth.
21. (Original) The light emitting diode as defined in claim 11, wherein:  
the AlGaAs layer is formed at a V/III ratio in raw materials of 50 or less at the time of  
growth.
22. (Original) The light emitting diode as defined in claim 11, wherein:  
the transparent conductive film is made of indium tin oxide.
23. (Original) The light emitting diode as defined in claim 11, wherein:  
the light-emitting region is made of  $(\text{Al}_x\text{Ga}_{1-x})_y\text{In}_{1-y}\text{P}$  ( $0 \leq x \leq 1$ ,  $0 \leq y \leq 1$ ).